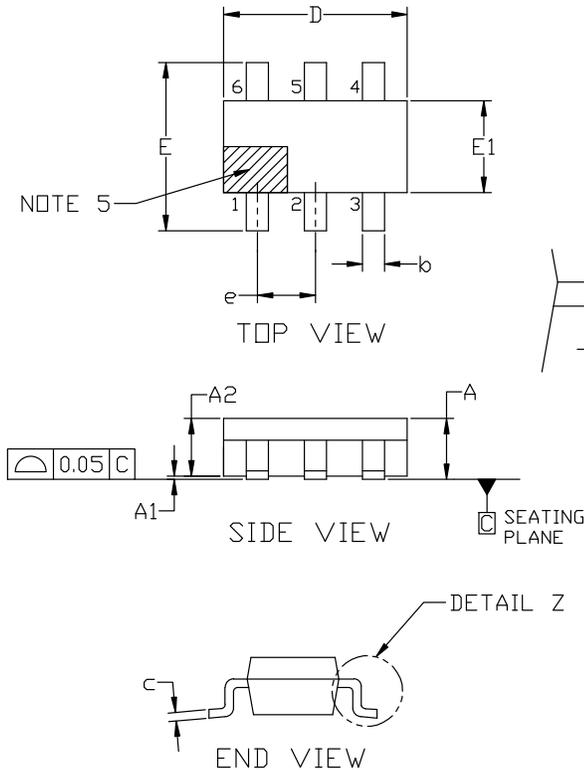




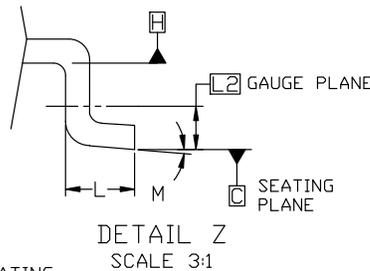
TSOP-6 3.00x1.50x0.90, 0.95P  
CASE 318G  
ISSUE W

DATE 26 FEB 2024

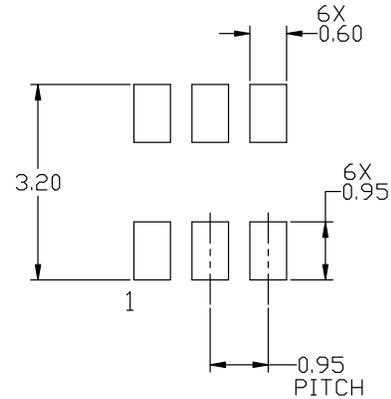


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM H.
5. PIN 1 INDICATOR MUST BE LOCATED IN THE INDICATED ZONE



MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.01	0.06	0.10
A2	0.80	0.90	1.00
b	0.25	0.38	0.50
c	0.10	0.18	0.26
D	2.90	3.00	3.10
E	2.50	2.75	3.00
E1	1.30	1.50	1.70
e	0.85	0.95	1.05
L	0.20	0.40	0.60
L2	0.25 BSC		
M	0°	---	10°



RECOMMENDED MOUNTING FOOTPRINT

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference manual, SOLDERRM/D.

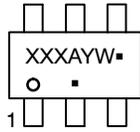
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DESCRIPTION:	TSOP-6 3.00x1.50x0.90, 0.95P	PAGE 1 OF 2

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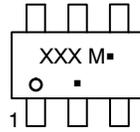
**TSOP-6 3.00x1.50x0.90, 0.95P**  
**CASE 318G**  
**ISSUE W**

DATE 26 FEB 2024

**GENERIC  
MARKING DIAGRAM\***



**IC**



**STANDARD**

XXX = Specific Device Code	XXX = Specific Device Code
A = Assembly Location	M = Date Code
Y = Year	▪ = Pb-Free Package
W = Work Week	
▪ = Pb-Free Package	

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

- |   |   |  |  |  |   |
|---|---|--|--|--|---|
| <p><b>STYLE 1:</b><br/> PIN 1. DRAIN<br/> 2. DRAIN<br/> 3. GATE<br/> 4. SOURCE<br/> 5. DRAIN<br/> 6. DRAIN</p>              | <p><b>STYLE 2:</b><br/> PIN 1. EMITTER 2<br/> 2. BASE 1<br/> 3. COLLECTOR 1<br/> 4. EMITTER 1<br/> 5. BASE 2<br/> 6. COLLECTOR 2</p>    | <p><b>STYLE 3:</b><br/> PIN 1. ENABLE<br/> 2. N/C<br/> 3. R BOOST<br/> 4. Vz<br/> 5. V in<br/> 6. V out</p>                            | <p><b>STYLE 4:</b><br/> PIN 1. N/C<br/> 2. V in<br/> 3. NOT USED<br/> 4. GROUND<br/> 5. ENABLE<br/> 6. LOAD</p>                | <p><b>STYLE 5:</b><br/> PIN 1. EMITTER 2<br/> 2. BASE 2<br/> 3. COLLECTOR 1<br/> 4. EMITTER 1<br/> 5. BASE 1<br/> 6. COLLECTOR 2</p> | <p><b>STYLE 6:</b><br/> PIN 1. COLLECTOR<br/> 2. COLLECTOR<br/> 3. BASE<br/> 4. EMITTER<br/> 5. COLLECTOR<br/> 6. COLLECTOR</p> |
| <p><b>STYLE 7:</b><br/> PIN 1. COLLECTOR<br/> 2. COLLECTOR<br/> 3. BASE<br/> 4. N/C<br/> 5. COLLECTOR<br/> 6. EMITTER</p>   | <p><b>STYLE 8:</b><br/> PIN 1. Vbus<br/> 2. D(in)<br/> 3. D(in)+<br/> 4. D(out)+<br/> 5. D(out)<br/> 6. GND</p>                         | <p><b>STYLE 9:</b><br/> PIN 1. LOW VOLTAGE GATE<br/> 2. DRAIN<br/> 3. SOURCE<br/> 4. DRAIN<br/> 5. DRAIN<br/> 6. HIGH VOLTAGE GATE</p> | <p><b>STYLE 10:</b><br/> PIN 1. D(OUT)+<br/> 2. GND<br/> 3. D(OUT)-<br/> 4. D(IN)-<br/> 5. VBUS<br/> 6. D(IN)+</p>             | <p><b>STYLE 11:</b><br/> PIN 1. SOURCE 1<br/> 2. DRAIN 2<br/> 3. DRAIN 2<br/> 4. SOURCE 2<br/> 5. GATE 1<br/> 6. DRAIN 1/GATE 2</p>  | <p><b>STYLE 12:</b><br/> PIN 1. I/O<br/> 2. GROUND<br/> 3. I/O<br/> 4. I/O<br/> 5. VCC<br/> 6. I/O</p>                          |
| <p><b>STYLE 13:</b><br/> PIN 1. GATE 1<br/> 2. SOURCE 2<br/> 3. GATE 2<br/> 4. DRAIN 2<br/> 5. SOURCE 1<br/> 6. DRAIN 1</p> | <p><b>STYLE 14:</b><br/> PIN 1. ANODE<br/> 2. SOURCE<br/> 3. GATE<br/> 4. CATHODE/DRAIN<br/> 5. CATHODE/DRAIN<br/> 6. CATHODE/DRAIN</p> | <p><b>STYLE 15:</b><br/> PIN 1. ANODE<br/> 2. SOURCE<br/> 3. GATE<br/> 4. DRAIN<br/> 5. N/C<br/> 6. CATHODE</p>                        | <p><b>STYLE 16:</b><br/> PIN 1. ANODE/CATHODE<br/> 2. BASE<br/> 3. EMITTER<br/> 4. COLLECTOR<br/> 5. ANODE<br/> 6. CATHODE</p> | <p><b>STYLE 17:</b><br/> PIN 1. EMITTER<br/> 2. BASE<br/> 3. ANODE/CATHODE<br/> 4. ANODE<br/> 5. CATHODE<br/> 6. COLLECTOR</p>       |   |

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